

RELIABILITY REPORT
FOR
MAX6520EUR+T
PLASTIC ENCAPSULATED DEVICES

April 8, 2011

MAXIM INTEGRATED PRODUCTS

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Conclusion

The MAX6520EUR+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6520 is the lowest-power 1.2V, precision, three-terminal voltage reference offered in a SOT23-3 package. Ideal for 3V battery-powered equipment where power conservation is critical, the MAX6520 is a low-power alternative to existing two-terminal shunt references. Unlike two-terminal references that throw away battery current and require an external series resistor, the MAX6520 has a 70 μ A maximum supply current (typically only 50 μ A) that is independent of the input voltage. This feature translates to maximum efficiency at all battery voltages. The MAX6520 operates from a supply voltage as low as 2.4V, and initial accuracy is $\pm 1\%$ for the SOT23 package.

Output voltage temperature coefficient is typically only 25ppm/ $^{\circ}$ C, and is guaranteed to be less than 50ppm/ $^{\circ}$ C in the SOT23 package.

II. Manufacturing Information

A. Description/Function:	50ppm/°C, SOT23, 3-Terminal, 1.2V Voltage Reference
B. Process:	S3
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1Imisr4
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0136
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250°C/W
K. Single Layer Theta Jc:	130°C/W
L. Multi Layer Theta Ja:	336°C/W
M. Multi Layer Theta Jc:	110.1°C/W

IV. Die Information

A. Dimensions:	31 X 44 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the S3 Process results in a FIT Rate of 0.04 @ 25C and 0.69 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD lot XHIABB003C D/C 9638, Latch-Up lot NHIACQ002F D/C 9903)

The RF19 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX6520EUR+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NHIACX002C, D/C 9934

Note 1: Life Test Data may represent plastic DIP qualification lots.